

09-06-2001

FLH Ref. No.: 450104-03011



ET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

101834909

To the Honorable Commissioner of Patents and Trademarks

Attached original documents or copy thereof.

1. Name of conveying party(ies)

Toshio TOOYAMA, Kenichi TOMITSUKA, Shohei MAWATARI, Tomotake
KAGAYA, Eihiko MURAMATSU

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name:

SONY CORPORATION
7-35 Kitashinagawa 6-chome
Shinagawa-Ku, Tokyo 141-0001, Japan

and

SENJU METAL INDUSTRY CO. LTD.
23 Senju-Hashido-Cho, Adachi-Ku
Tokyo, Japan

3. Nature of conveyance:

- ☒ Assignment
☐ Security Agreement
☐ Merger
☐ Change of Name
☐ Other

Execution Date(s): July 25, July 18, August 10, August 10
and August 18, 2001Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of
the application is:A. Patent Application No.(s) 09/788,154 filed February 16, 2001Additional numbers attached? ☐ Yes ☒ No5. Name and address of party to whom correspondence
concerning document should be mailed:

Name: WILLIAM S. FROMMER

Internal Address: FROMMER LAWRENCE & HAUG LLP

Street Address: 745 FIFTH AVENUE

City: NEW YORK State: N.Y. Zip: 101516. Total number of applications and
patents involved

1

7. Total fee (37 CFR 3.41) \$ 40.00
☒ Enclosed
☐ Authorized to be charged to
deposit account 50-03208. Deposit account number:
(Attach duplicate copy of this page if paying by deposit
account)

Do not use this space

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true
copy of the original document.

GLENN F. SAVIT

Name of Person Signing

Signature

August 28, 2001

Date

Total number of pages including cover
sheet, attachments, and document: 3

09/05/2001 LNUELLER 00000230 09788154

01 FC:581

40.00 OP

Do not detach this portion

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
Box Assignments
Washington, D.C. 20231

Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded,
including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet.
Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems,
PK2-1000C, Washington, D.C. 20231, and to the Office of Management and Budget, Paperwork Reduction Project (0651-0011),
Washington, D.C. 20503.

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

METHOD FOR SEPARATING OXIDE FROM DROSS, DEVICE FOR SEPARATING OXIDE FROM DROSS, AND JET SOLDER TANK

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo 141, Japan and SENJU METAL INDUSTRY CO. LTD., a 23 Senju-Hashido-Cho, Adachi-Ku, corporation, with offices at 23 Senju-Hashido-Cho, Adachi-Ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 09/788,154, Filing Date: February 16, 2001.

This assignment executed on the dates indicated below.

Toshio TOOYAMA

Name of first or sole inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of first or sole inventor

Toshio Toyama
Signature of first or sole inventor

July 25, 2001
Date of this assignment

Kenichi TOMITSUKA

Name of second inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Kenichi Tomitsuka
Signature of second inventor

July 18, 2001
Date of this assignment

Shohei MAWATARI

Name of third inventor

Execution date of U.S. Patent Application

Residence of third inventor

Shohei Mawatari
Signature of third inventor

Aug. 10, 2001
Date of this assignment

ADDITIONAL INVENTORS

Tomotake KAGAYA

Name of fourth inventor

Execution date of U.S. Patent Application

Saitama, Japan

Residence of fourth inventor

Signature of fourth inventor

Aug. 10. 2001

Date of this assignment

Eihiko MURAMATSU

Name of fifth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fifth inventor

Signature of fifth inventor

Aug. 18. 2001

Date of this assignment